

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT								
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT								
<b>CONVEYING PARTY DATA</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Won Joo Yun</td> <td>12/11/2007</td> </tr> <tr> <td>Hyun Woo Lee</td> <td>12/11/2007</td> </tr> <tr> <td>Dong Suk Shin</td> <td>12/11/2007</td> </tr> </tbody> </table>		Name	Execution Date	Won Joo Yun	12/11/2007	Hyun Woo Lee	12/11/2007	Dong Suk Shin	12/11/2007
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Won Joo Yun	12/11/2007								
Hyun Woo Lee	12/11/2007								
Dong Suk Shin	12/11/2007								
<b>RECEIVING PARTY DATA</b>									
<b>Name:</b>	HYNIX SEMICONDUCTOR INC.								
<b>Street Address:</b>	San 136-1, Ami-ri, Bubal-eub								
<b>Internal Address:</b>	Gyeonggi-do								
<b>City:</b>	Ichon								
<b>State/Country:</b>	REPUBLIC OF KOREA								
<b>Postal Code:</b>	467-860								
<b>PROPERTY NUMBERS Total: 1</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11964802</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11964802				
Property Type	Number								
Application Number:	11964802								
<b>CORRESPONDENCE DATA</b>									
<b>Fax Number:</b>	(214)978-3099								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
<b>Email:</b>	scarlett.k.pereida@bakernet.com								
<b>Correspondent Name:</b>	Noel C. Gillespie								
<b>Address Line 1:</b>	2001 Ross Avenue, Suite 2300								
<b>Address Line 2:</b>	Baker & McKenzie								
<b>Address Line 4:</b>	Dallas, TEXAS 75201								
<b>ATTORNEY DOCKET NUMBER:</b>	95210324.200133								
<b>NAME OF SUBMITTER:</b>	Noel C. Gillespie								
<p>Total Attachments: 3          source=200133_Assignment#page1.tif</p>									

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## ASSIGNMENT

WHEREAS, I the undersigned inventor of residence as listed, have invented certain new and useful improvements as below entitled, for which an application for United States Letters Patent is made, said application having been designated as set forth below and filed on or about the date set forth below; and

WHEREAS, Hynix Semiconductor Inc. (hereinafter referred to as "Assignee"),

with an address of: San 136-1, Ami-ri, Bubal-eub, Ichon-si,  
Gyeonggi-do 467-860, Republic of Korea

desires to acquire the entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent(s) that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I assign to Assignee, all right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, continuations, continuations-in-part and extensions thereof; and I authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also assign to Assignee, all right, title and interest in and to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world, including all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in Assignee.

I will communicate to Assignee any facts known to us respecting any improvements; and, at the expense of Assignee, I will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in Assignee and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

This Assignment shall be binding on the parties' successors, assigns and legal representatives.

**Invention Name:** POWER CONTROL CIRCUIT, METHOD OF CONTROLLING POWER CONTROL CIRCUIT, AND DLL CIRCUIT INCLUDING POWER CONTROL CIRCUIT

**Serial No.:** \_\_\_\_\_

**Date Filed:** \_\_\_\_\_

I hereby grant JOHN G. FLAIM, Registration No. 37,323, BRIAN C. McCORMACK, Registration No. 36,601, WILLIAM D. McSPADDEN, Registration No. 44,234, JAMES H. ORTEGA, Registration No. 50,554, RICHARD V. WELLS, Registration No. 53,757, HOWARD WISNIA, Registration No. 37,502, NOEL C. GILLESPIE, Registration No. 47,596, ROGER C. KUAN, Registration No. 56,558, KEVIN O'BRIEN, Registration No. 30,578, JAMES P. CONLEY, Registration No. 52,459, and all practitioners with the firm of Baker & McKenzie LLP (Customer Number 23562) with an office at 2001 Ross Avenue, Suite 2300, Dallas, TX 75201, the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

The undersigned further declares that all statements made herein of his/her own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful and false statements may jeopardize the validity of the application or any patent issued thereon.

**Signature of Inventor:** Won Joo Yun

**Inventor(s) Name:** Won Joo, YUN

**Residence:** San 136-1, Ami-ri, Bubal-eub, Ichon-si, Gyeonggi-do 467-860, Republic of Korea

**Citizenship:** Korean

**Date:** Dec. 11, 2007

Signature of Inventor: Hyun Woo Lee

Inventor(s) Name: Hyun Woo, LEE

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,  
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: Dec. 11, 2007

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Signature of Inventor: Dongsuk Shin

Inventor(s) Name: Dong Suk, SHIN

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,  
Gyeonggi-do 467-860, Republic of Korea

Citizenship: Korean

Date: Dec. 11, 2007

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